PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Patrick REILLY	05/17/2012
Shahid SHAIKH	05/15/2012
Tersem SUMMAN	05/15/2012
Deenesh PADHI	06/10/2012
Sanjeev BALUJA	05/15/2012
Juan Carlos ROCHA-ALVAREZ	05/17/2012
Thomas NOWAK	05/15/2012
Bok Hoen KIM	05/15/2012
Derek R. WITTY	05/16/2012

RECEIVING PARTY DATA

Name:	APPLIED MATERIALS, INC.
Street Address:	3050 Bowers Avenue
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13468776

OP $40.00 13468776

CORRESPONDENCE DATA

Fax Number:	(713)623-4846
Phone:	7136234844
Email:	psdocketing@pattersonsheridan.com, nhouston@pattersonsheridan.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: PATTERSON & SHERIDAN, LLP - - APPM/TX
Address Line 1: 3040 POST OAK BOULEVARD, SUITE 1500

Address Line 4:	HOUSTON, TEXAS 77056
ATTORNEY DOCKET NUMBER:	APPM/016249US/NHOUSTON
NAME OF SUBMITTER:	Keith M. Tackett

Total Attachments: 6
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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

PPR

1)	Patrick REILLY 10772 Ruthven Ln ~~6552 Cottonwood Circle, Apt. B.~~ Dublin, California ~~95134~~ 94568	2)	Shahid SHAIKH 1885 Cabrillo Avenue Santa Clara, California 95050
3)	Tersem SUMMAN 43 Chapelhaven Court San Jose, California 95111	4)	Deenesh PADHI 1066 Reed Ave, #12 Sunnyvale, California 94086
5)	Sanjeev BALUJA 2198 Anthony Drive Campbell, California 95008	6)	Juan Carlos ROCHA-ALVAREZ 18 Cedar Street San Carlos, California 94070
7)	Thomas NOWAK 20677 Forge Way, #217 Cupertino, California 95014	8)	Bok Hoen KIM 1116 Sterling Gate Drive San Jose, California 95120
9)	Derek R. WITTY 1049 Geronimo Court Fremont, California 94539		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

DEPOSITION OF AN AMORPHOUS CARBON LAYER WITH HIGH FILM DENSITY AND HIGH ETCH SELECTIVITY

for which application for Letters Patent in the United States was filed on May 10, 2012, under Serial No. 13/468,776, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of @@@, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) 5/17/12 (DATE)
Patrick REILLY

2) ____________ (DATE)
Shahid SHAIKH

3) ____________ (DATE)
Tersem SUMMAN

4) ____________ (DATE)
Deenesh PADHI

5) ____________ (DATE)
Sanjeev BALUJA

6) ____________ (DATE)
Juan Carlos ROCHA-ALVAREZ

7) ____________ (DATE)
Thomas NOWAK

8) ____________ (DATE)
Bok Hoen KIM

9) ____________ (DATE)
Derek R. WITTY

Atty Dkt No.:016249/DSM/LOW K/JW

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7) 5/15/2012 (DATE) ____________ Thomas NOWAK

8) 5/15/2012 (DATE) ____________ Bok Hoen KIM

9) 5/16/12 (DATE) Derek R. Witty ____________ Derek R. WITTY

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